

Features :

- Isolated mounting base 2500V~
- Pressure contact technology with Increased power cycling capability
- Space and weight saving

Typical Applications

- Various rectifiers
- DC supply for PWM inverter

V _{RSM}	V _{RRM}	Type & Outline
900V	800V	MDx800-08-411F3
1100V	1000V	MDx800-10-411F3
1300V	1200V	MDx800-12-411F3
1500V	1400V	MDx800-14-411F3
1700V	1600V	MDx800-16-411F3
1900V	1800V	MDx800-18-411F3

SYMBOL	CHARACTERISTIC	TEST CONDITIONS	T _j (°C)	VALUE			UNIT
				Min	Type	Max	
I _{F(AV)}	Mean forward current	180° half sine wave 50Hz Single side water cooled, T _c =60°C	150			800	A
I _{F(RMS)}	RMS forward current		150			1256	A
I _{RRM}	Repetitive peak current	at V _{RRM}	150			40	mA
I _{FSM}	Surge forward current	10ms half sine wave	150			20	kA
I ² t	I ² t for fusing coordination	V _R =0.6V _{RRM}				2000	A ² s*10 ³
V _{FO}	Threshold voltage		150			0.75	V
r _F	Forward slope resistance					0.34	mΩ
V _{FM}	Peak forward voltage	I _{FM} =2400A	25			1.72	V
R _{th(j-c)}	Thermal resistance Junction to case	At 180° sine Single side cooled per chip				0.080	°C /W
R _{th(c-h)}	Thermal resistance case to heat sink	At 180° sine Single side cooled per chip				0.024	°C /W
V _{ISO}	Isolation voltage	50Hz,R.M.S,t=1min, I _{ISO} :1mA(max)		2500			V
F _m	Terminal connection torque(M10)				14.0		N·m
	Mounting torque(M6)				12.0		N·m
T _{stg}	Stored temperature			-40		125	°C
W _t	Weight				3460		g
Outline	411F3						

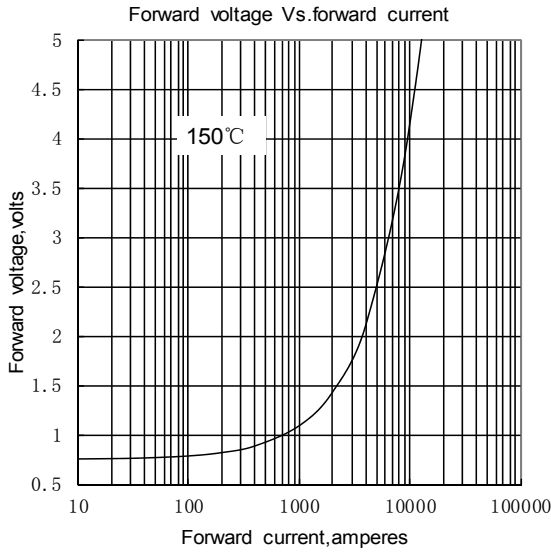


Fig.1

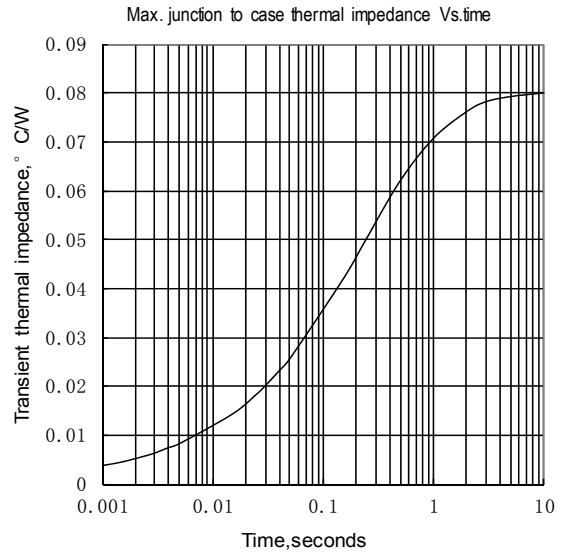


Fig.2

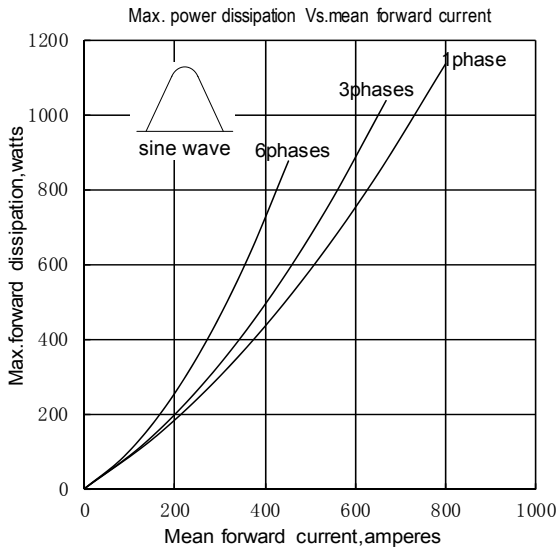


Fig.3

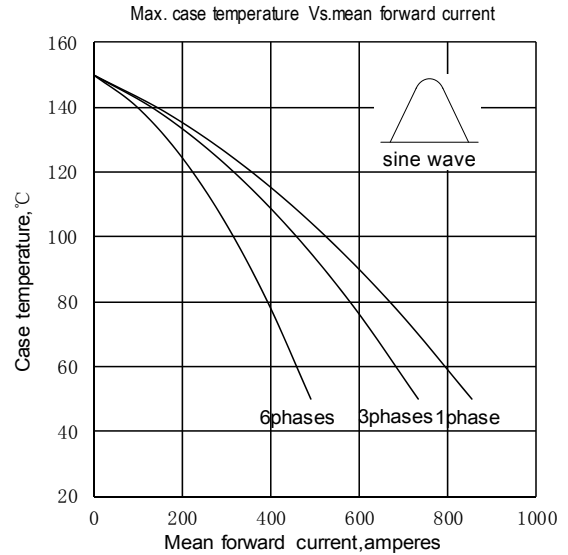


Fig.4

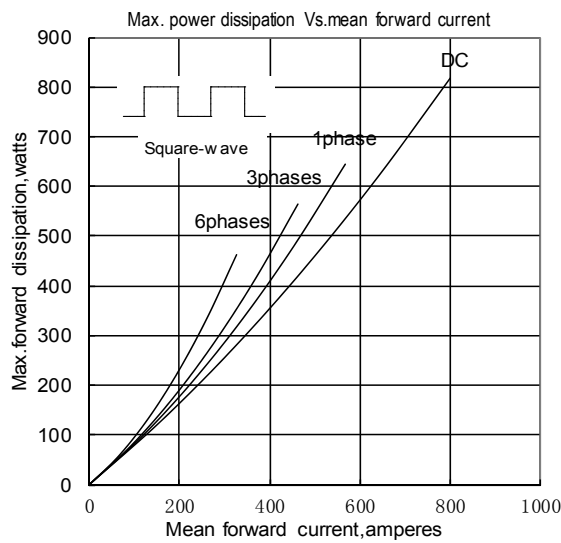


Fig.5

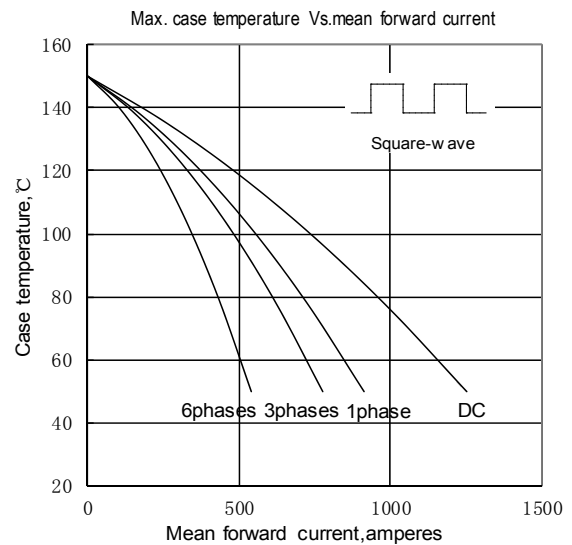


Fig.6

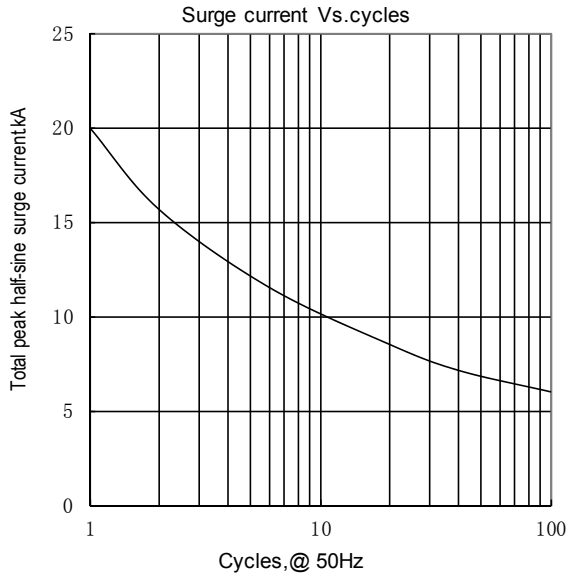


Fig.7

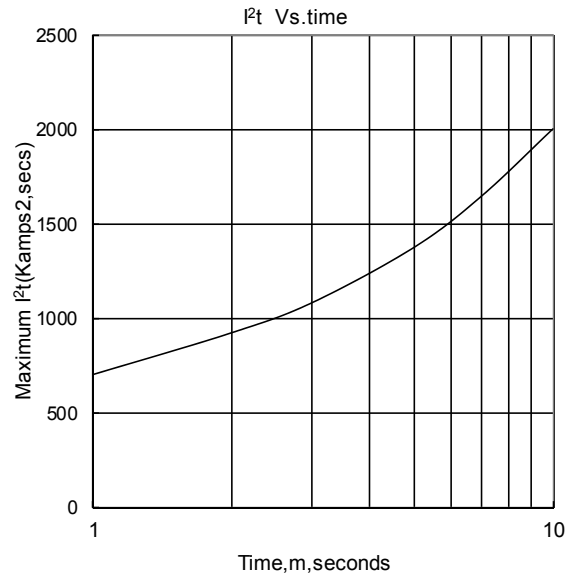
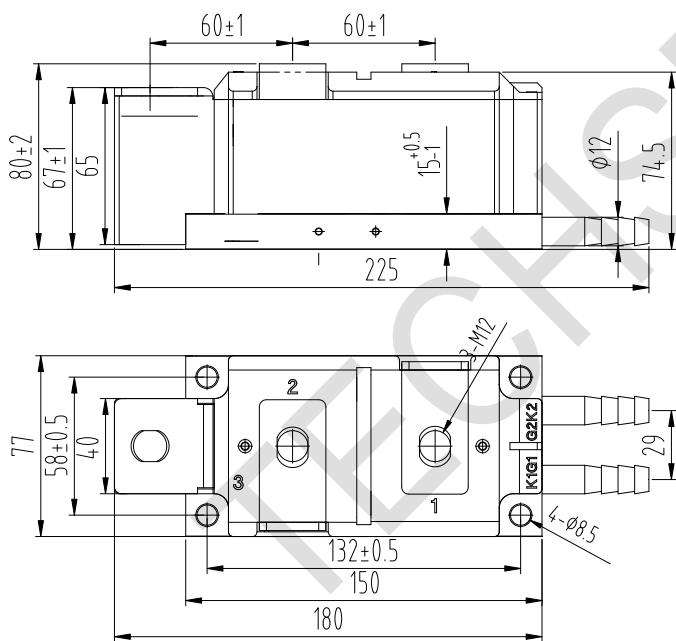


Fig.8

Outline:



MDC

MDA

MDK

MD

